

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Masayuki NAKAMOTO

SERIAL NO: NEW APPLICATION

GAU:

FILED: HEREWITH

EXAMINER:

FOR: FIELD EMISSION COLD CATHODE DEVICE OF LATERAL TYPE



INFORMATION DISCLOSURE/RELATED CASE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☒ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.


Marvin J. Spivak
Registration No. 24,913

C. Irvin McClelland
Registration Number 21,124



22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 10/98)

11017 U.S. PTO
09/987862
11/16/01

LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent No.</u>	<u>Filing or Issue Date</u>	<u>Status or Patentee</u>
PER CLIENT	5,499,938	03/19/96	NAKAMOTO et al.
PER CLIENT	5,727,976	03/17/98	NAKAMOTO et al.
PER CLIENT	5,749,762	05/12/98	NAKAMOTO et al.
0039-5336-2 SRD	5,977,693	11/02/99	NAKAMOTO et al.
0039-5536-0 SRD	5,747,926	05/05/98	NAKAMOTO et al.
0039-5755-2 SRD	5,786,656	07/28/98	HASEGAWA et al.
0039-6009-2 SRD	5,808,408	09/15/98	NAKAMOTO
0039-6267-3 SRD	6,097,138	08/01/00	NAKAMOTO
0039-6277-2 SRD	6,031,328	02/29/00	NAKAMOTO
0039-6280-2 SRD	5,834,324	11/10/98	NAKAMOTO
0039-7397-2 SRD	09/414,840	10/08/99	PENDING
0039-7618-2 RD	09/526,468	03/15/00	PENDING
0039-7640-2S	09/531,158	03/17/00	PENDING
204928US2 SRD	09/810,649	03/19/01	PENDING

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IN RE APPLICATION OF: Masayuki NAKAMOTO

SERIAL NO.: New Application

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FOR: FIELD EMISSION COLD CATHODE DEVICE OF LATERAL TYPE



STATEMENT OF RELEVANCY

Reference AW on Form PTO-1449:

This reference relates to field emitters using carbon nanotubes. However, they do not use electro-plating layer, especially resist-ballasting electro-plating layer and substrates, but use carbon paste and a hairpin-shaped tungsten or nichrome wire for supporting carbon nanotubes.

Reference AX on Form PTO-1449:

This reference also relates to field emitters using carbon nanotubes. However, they do not have electro-plating layer, especially, resist-ballasting electro-plating layer, but have paste layer for bonding carbon nanotubes to substrates.

Reference AZ on Form PTO-1449:

This reference also relates to field emitters using carbon nanotubes. However, they do not use electro-plating but screen printing with binder and slurries for bonding carbon nanotubes to substrates. Moreover, they do not have electro-plating layer, especially, resist-ballasting electro plating layer.